

RENESAS

HSB285S

Silicon Schottky Barrier Diode for High frequency detection

REJ03G0010-0100Z

Rev.1.00

Apr,16,2003

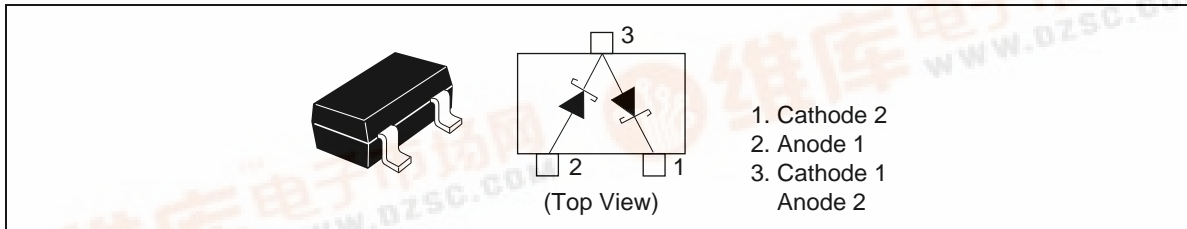
Features

- Low forward voltage, Low capacitance and High detection sensitivity.
- HSB285S which is interconnected in series configuration. is designed for voltage doubler use.
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code
HSB285S	S3	CMPAK

Pin Arrangement



HSB285S

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	2	V
Average rectified current	I _O * ¹	5	mA
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note: 1. Per one device

Electrical Characteristics *¹

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V _{F1}	—	—	0.15	V	I _F = 0.1 mA
	V _{F2}	—	—	0.27		I _F = 1 mA
Capacitance	C	—	0.3	—	pF	V _R = 1 V, f = 1 MHz
ESD-Capability * ²	—	10	—	—	V	C = 200 pF, R _L = 0 Ω, Both forward and reverse direction 1 pulse.

Notes: 1. Per one device

2. Failure criterion ; I_R ≥ 100 μA at V_R = 0.5 V

Main Characteristic

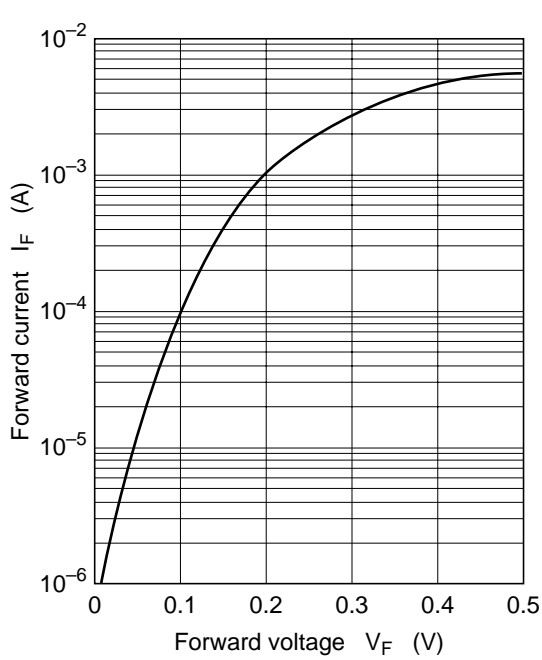


Fig.1 Forward current vs. Forward voltage

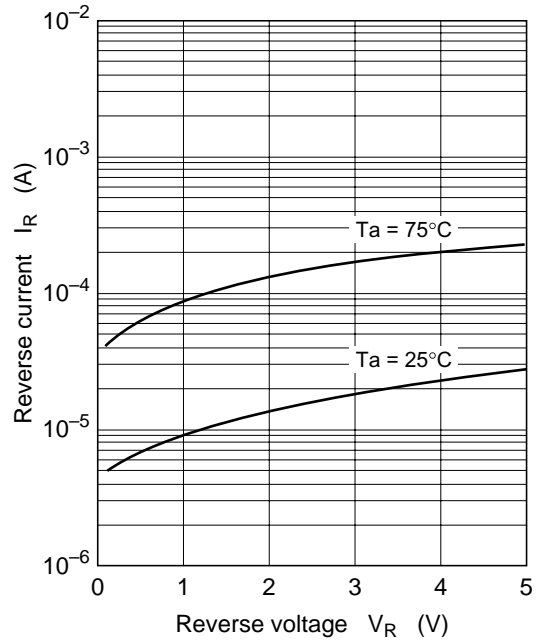


Fig.2 Reverse current vs. Reverse voltage

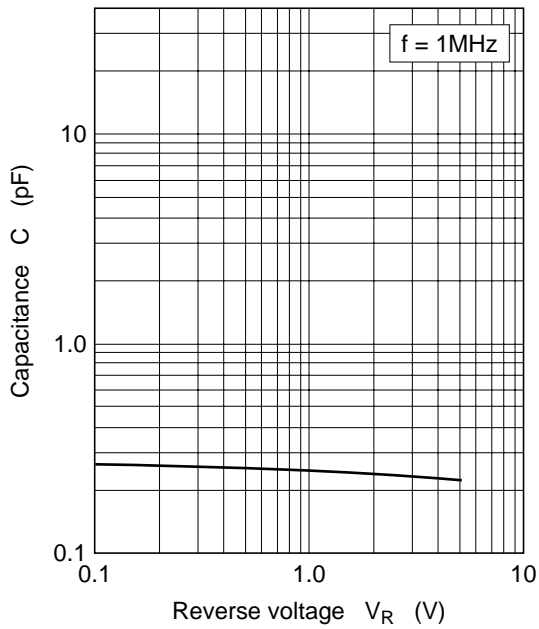
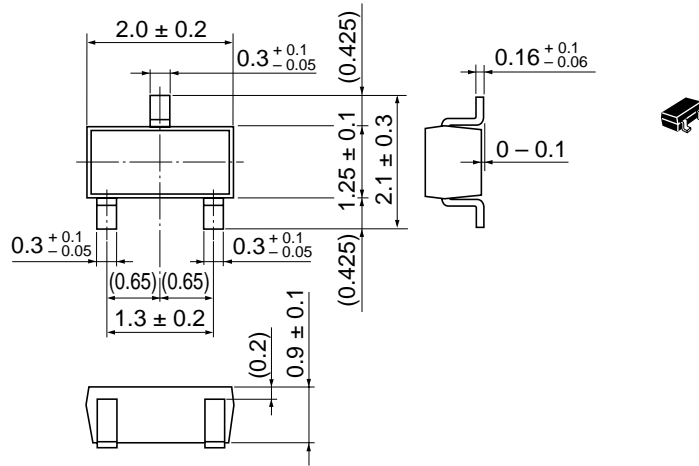


Fig.3 Capacitance vs. Reverse voltage

HSB285S

Package Dimensions

As of January, 2003
Unit: mm



Package Code	CMPAK
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.006 g

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